

Product Specification for MZDD*G6LAB20 in manufacturing phase ASSY
Plant Z7GA SC - UTAC Thai Limited 997G
Parent Company STMICROELECTRONICS

Techno.(package) TX UFDFPN 1X1.3 4L PITCH 0.5 7986858

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Header

Moisture Sensitivity 1(UNLIMITED at <=30C/85%RH)
Peak body Temperature = 260 DEGREES CELSIUS
Eco Level = ECOPACK2/ROHS
EcoPack device as per Document Ref : 7191395
Eco Level Details = ECOPACK2/ROHS - No exemption (Code 20 G)
Second_lvl_intct = e4 Precious metal (Ag, Au, NiPdAu)

APPENDIX DOCUMENT

PXA 978601 for product MZDD*G6LAB20

ADCS /F/C-ASSS /7991026 /FCA&CONTROL PLANS FOR UQFN/UDFN - UTAC

Product Specification for assembly is based on corporate
document CD17559047

RL ESD Sensitivity Class	: Class II[500,1999]
Human Body Model sensitivity	: 2000 volt
Charged Device Model sensitivity	: 500 volt
Machine Model sensitivity(optional)	: 200 volt

INSTRUCTION NOTES

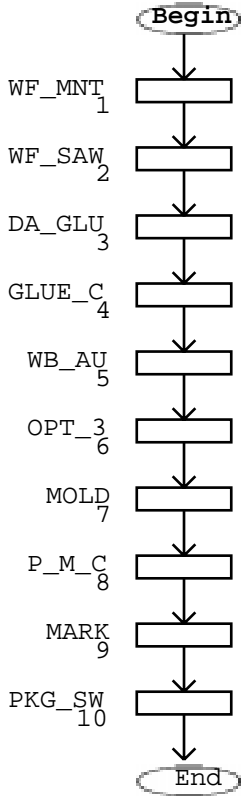
USE UTAC FCA UQFN/UDFN PROCESS FLOW
CP-STM-001/UQFN

Routing types

Routing Type : 58319

MAIN branch

MZDD*G6LAB20



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Components

Raw Material list

<u>Code</u>	<u>Description</u>	<u>Source</u>
5FN0051*	C.O.L., PPF, 4L UDFN FRAME, 1X1.3 - NSEB #FN0051	
MNAM002*	Sumitomo G-770HCD	
PNZT000*	8006NS (Non-Conductive Epoxy)	
WNQ7000*	Bond Wire 1.0 mil Au	

DIE LIST :

<u>FEP</u>	<u>DIE</u>	<u>Qty</u>	<u>Ident</u>	<u>WaferMap from EWS</u>	<u>EWSI</u>	<u>Bondg</u>	<u>Wafer</u>
XG6LAB20	PG6LAB20	1	STLM20	YS	CD00210465		CG6LAB20

<Die# in Mount & Bonding Diag NOT defined(FEP data) Mandatory Flag= N>

DIE FEATURES for FEP XG6LAB20 DIE CODE PG6LAB20 DIE IDENT STLM20

STEPPING DIE SIZE(X,Y) : 720,710 UM
 PATTERN STEPPING(X,Y) : 720,710 UM
 WAFER THICKNESS : 381+/-10 UM
 SAWING STREET WIDTH(X,Y): 60,60 UM
 DIE FINISH FRONT SIDE : PSG+Silicon Nitride+Polyimide
 DIE FINISH BACK SIDE : RAW SILICON - BACK GRINDING
 Die Attach Target Count : 4
 DIFF PROCESS FAMILY : TZ HCMOS4TZ
 MASKING METHOD : Mixed GROOVE NB : 1

<u>WIRE BOND PAD METAL</u>	<u>COMPOSITION</u>	<u>THICKNESS</u>
Metal 1	Ti/TiNTi/AlSiCu/TiN	0.840 UM
Metal 2	Ti/AlSiCu/TiN	0.980 UM

CRITICAL PAD DIMENSIONS

MIN BOND PAD PITCH : 355 UM
 STAGGERED PADS : N
 Circuit Under Pad : NO
 DEVICE CLASS : C1-Sb_C1 C1 as in 0018063

<u>Geometry</u>	<u>Open (x,y)</u>	<u># of pad</u>	<u>Placement (%)</u>	<u>Nb of Wire per bond pad</u>
1 Other	70,70 UM	4	100% IN B.P.O.	3

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Manufacturing Instructions

Instr for step (MAIN WB_AU 5) Wire Bonding Gold/Alt 1/Routg 58319

Specification Ref	7990494 REV D MBD, GHLAB20, G6LA, 4L UDFN TX PKG - U TAC 997G
Operating comment	See * bonding note on bond diagram, where to start bonding.
Nb Bond Wire	3
Ground Wire	N

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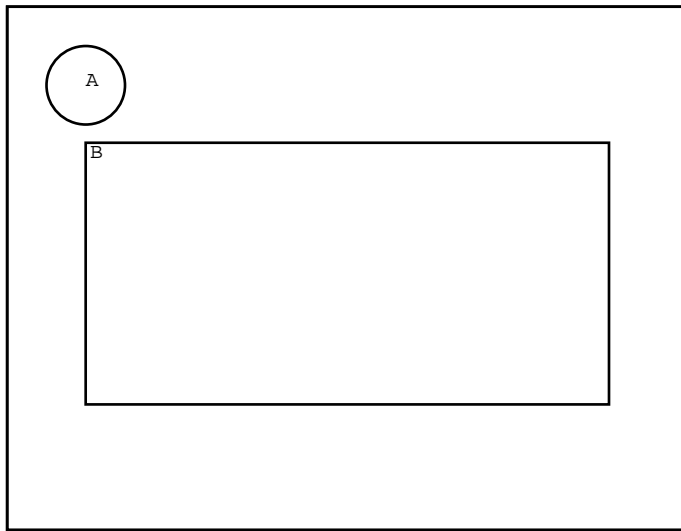
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Instr for step (MAIN MARK 9) Marking/Alt /Routg 58319

STEP TYPE Marking

Marking Composition CD00112197 4L DFN 1.0X1.3MM
1 LINE, 2 CHARACTERS

PACKAGE FACE : TOP



LEGEND

- Unmarkable Surface
- Marking Composition Field

A-45281 - DOT
B-45290 - MARKING AREA

<u>CODE</u>	<u>COMPOSN FLD TYPE</u>	<u>MARKING VALUE</u>
45290	MARKING AREA	20